



SPECIFICATION

(Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL03C0R5BA3GNNC

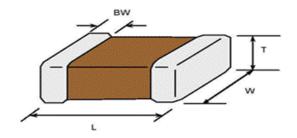
• Product : Multi-layer Ceramic Capacitor • Description : CAP, 0.5pF, 25V, ±0.1pF, C0G, 0201

A. Samsung Part Number

<u>CL</u> <u>03</u> <u>C</u> <u>0R5</u> <u>B</u> <u>A</u> <u>3</u> <u>G</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Cera	amic Capacitor	
② Size	0201 (inch code)	L: 0.60 ± 0.03 mm	W: 0.30 ± 0.03 mm
3 Dielectric	C0G	8 Inner electrode	Cu
④ Capacitance	0.5 pF	Termination	Cu
⑤ Capacitance	±0.1 pF	Plating	Sn 100% (Pb Free)
tolerance		Product	Normal
6 Rated Voltage	25 V	Special	Reserved for future use
① Thickness	0.30 ± 0.03 mm	① Packaging	Cardboard Type, 7" reel

B. Structure and dimension



Samsung P/N	Dimension(mm)				
(Lead Free)	L	W	Т	BW	
CL03C0R5BA3GNNC	0.60±0.03	0.30±0.03	0.30±0.03	0.15±0.05	

C. Samsung Reliability Test and Judgement condition

Capacitance Within specified tolerance 1Mb±10% 0.5~5Vrms Q 410 min Insulation 10,000Mohm or 500Mohm·µF Rated Voltage 60~120 sec. Resistance Whichever is smaller Rated Voltage 60~120 sec. Appearance No abnormal exterior appearance Microscope (×10) Withstanding No dielectric breakdown or mechanical breakdown 300% of the rated voltage Temperature C0G (From -55°C to 125°C, Capacitance change should be within ±30PPM/°C) Adhesive Strength of Termination No peeling shall be occur on the terminal electrode 200g·F, for 10±1 sec. Bending Strength Capacitance change : with 1.0mm/sec. Bending to the limit (1mm) with 1.0mm/sec. Solderability More than 75% of terminal surface is to be soldered newly SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.) Resistance to Capacitance change : Solder pot : 270±5°C, 10±1sec.
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Adhesive Strength of Termination Bending Strength Work peeling shall be occur on the terminal electrode Capacitance change: Within ±5% or ±0.5pF whichever is larger More than 75% of terminal surface is to be soldered newly More than 75% of terminal surface Work peeling shall be occur on the terminal sec. Bending to the limit (1mm) With 1.0mm/sec. SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating: 80~120°C for 10~30sec.)
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Resistance to Capacitance change : Solder pot : 270+5°C, 10+1sec.
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contained on the cont
Soldering heat within ±2.5% or ±0.25pF whichever is larger
Tan δ, IR : initial spec.
Vibration Test Capacitance change : Amplitude : 1.5mm
within ±2.5% or ±0.25pF whichever is larger From 10Hz to 55Hz (return : 1min.)
Tan δ , IR : initial spec. 2hours \times 3 direction (x, y, z)
Moisture Capacitance change : With rated voltage
Resistance within ±7.5% or ±0.75pF whichever is larger 40±2°C, 90~95%RH, 500+12/-0hrs
Q: 101.67 min
IR : 500Mohm or 25Mohm $\cdot \mu$ F
Whichever is smaller
High Temperature Capacitance change : With 200% of the rated voltage
Resistance within ±3% or ±0.3pF whichever is larger Max. operating temperature
Q: 205 min 1000+48/-0hrs
IR : 1,000Mohm or 50Mohm $\cdot \mu$ F
Whichever is smaller
Temperature Capacitance change : 1 cycle condition
Cycling within $\pm 2.5\%$ or $\pm 0.25 pF$ whichever is larger Min. operating temperature \rightarrow 25 °C
Tan δ , IR : initial spec. \rightarrow Max. operating temperature \rightarrow 25 $^{\circ}$ C
5 cycle test

^{*} The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature: 260+0/-5°C, 10sec. Max)

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

Disclaimer & Limitation of Use and Application

The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.

We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- ① Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- 4 Military equipment
- ⑤ Disaster prevention/crime prevention equipment
- 6 Power plant control equipment
- Atomic energy-related equipment
- Undersea equipment
- Traffic signal equipment
- Data-processing equipment
- ## Electric heating apparatus, burning equipment
- Safety equipment
- Any other applications with the same as or similar complexity or reliability to the applications